Switching Diode

### DA2J10700L

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**Panasonic** 

### Silicon epitaxial planar type

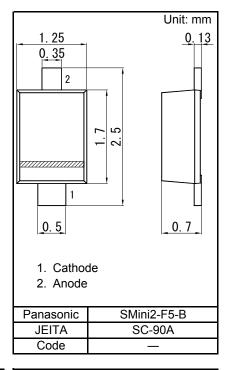
For high speed switching circuits DA3X107K in SMini2 type package

#### ■ Features

- High reverse voltage VR
- · Small reverse current IR
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: B1

#### ■ Packaging

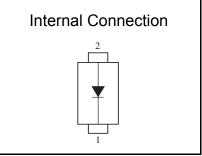
Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)



■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Reverse voltage	VR	300	V
Repetitive peak reverse voltage	VRRM	300	V
Forward current (Average)	IF(AV)	100	mA
Repetitive peak forwand current	IFRM	225	mA
Non-repetitive peak forward surge current *1	IFSM	500	mA
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1: t = 1 s



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Established: 2010-06-02 Revised: 2013-05-29 Doc No. TT4-EA-12605

Revision. 3

Switching Diode

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### ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 100 mA			1.2	V
Reverse current	IR	VR = 300 V			1.0	μA
Terminal capacitance	Ct	VR = 6 V, f = 1 MHz			3.0	pF
Reverse recovery time *1	trr	IF = 10 mA, VR = 6 V Irr = 0.25 x IR			60	ns

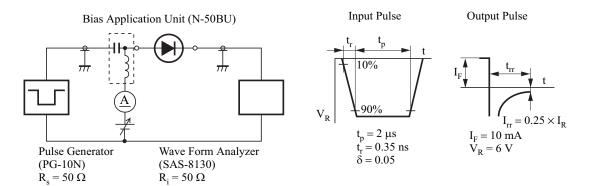
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

- 2. Absolute frequency of input and output is 20 MHz.
- 3. \*1: trr test circuit

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Revised

: 2013-05-29

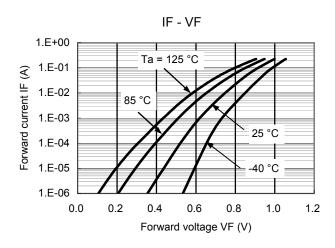


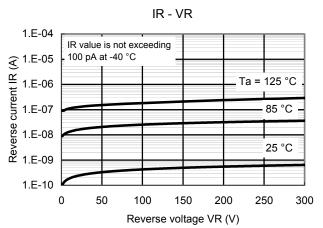
Revision. 3

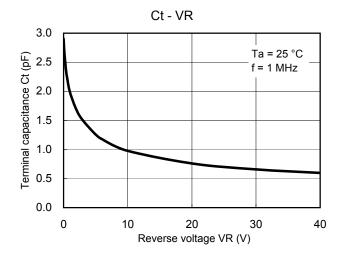
**Panasonic** 

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### Technical Data (reference)







Established: 2010-06-02 : 2013-05-29 Revised

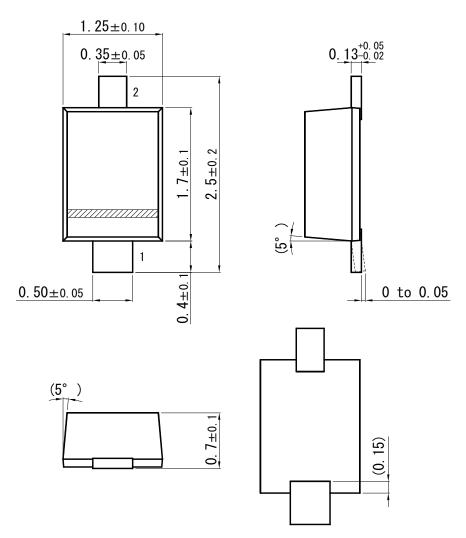
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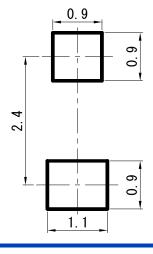
SMini2-F5-B

Unit: mm



■ Land Pattern (Reference) (Unit: mm)

Established: 2010-06-02 Revised: 2013-05-29



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